

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-14. (Canceled)

D4 15. (Currently Amended) A semiconductor device, comprising:

a semiconductor chip;

a substrate on which the semiconductor chip is mounted and which is formed by cutting apart a larger substrate; and

resin for sealing the semiconductor chip;

wherein the semiconductor device has side surfaces, each of the side surfaces ~~are~~ is flat, each of the side surfaces ~~are~~ is made of at least an edge surface of the substrate and an edge surface of the resin, the edge surfaces of the substrate and the resin are level with each other, a pair of the side surfaces make a corner portion, and a hole is formed in the substrate such that the substrate is indented at the corner portion further inward than a portion of the resin.

16. (Previously Amended) The semiconductor device as defined in claim 15,

wherein the substrate at the corner portion forms a shape that is indented in the opposite direction from the direction in which the corner portion protrudes, and thus an indented surface of the substrate is positioned further inward than the portion of the resin.

17. (Canceled)

18. (Previously Amended) The semiconductor device as defined in claim 15,

wherein an indented surface of the substrate is covered by the resin.

19. (Previously Amended) The semiconductor device as defined in claim 15,

wherein a cover is provided at the corner portion, between the substrate and the resin; and

wherein an indented surface of the substrate is exposed.

20. (Original) A circuit board on which is mounted the semiconductor device as defined in claim 15.

21. (Original) Electronic equipment provided with the semiconductor device as defined in claim 15.

22-28. (Canceled)

29. (Previously Added) The semiconductor device as defined in claim 15, wherein the hole is a through-hole.

30. (Cancelled).

31. (Currently Amended) A semiconductor device₁ comprising:

a semiconductor chip;

a substrate on which the semiconductor chip is mounted and which is formed by cutting apart a larger substrate; and

resin for sealing the semiconductor chip₂;

wherein the semiconductor device has side surfaces, each of the side surfaces ~~are~~is flat, each of the side surfaces ~~are~~is made of at least an edge surface of the substrate and an edge surface of the resin, ~~the edge surfaces of the substrate and the resin are level with each other,~~ a pair of the side surfaces make a corner portion, and the substrate has a thinner portion at the corner portion.

32. (New) A semiconductor device₁ comprising:

a semiconductor chip;

a substrate on which the semiconductor chip is mounted and which is formed by cutting apart a larger substrate; and

resin for sealing the semiconductor chip₂;

wherein the semiconductor device has side surfaces, each of the side surfaces is flat, each of the side surfaces is made of at least an edge surface of the substrate and an edge surface of the resin, a pair of the side surfaces make a corner portion, and a hole is

formed in the substrate such that the substrate is indented at the corner portion further inward than a portion of the resin.

33. (New) The semiconductor device as defined in claim 32, wherein the substrate has a thinner portion at the corner portion.

34. (New) A semiconductor device having side surfaces, each of the side surfaces being flat, a pair of the side surfaces making a corner portion, the semiconductor device comprising:

a semiconductor chip;

resin for sealing the semiconductor chip, the resin having an edge surface; and

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a substrate on which the semiconductor chip is mounted, the substrate having such a shape as to be obtained by cutting apart a larger substrate across a hole formed in the larger substrate, the substrate having an indented surface at the corner portion further inward than a portion of the resin, the indented surface being a portion of an inner surface of the hole,

wherein one of the side surfaces is made of at least an outline surface of the substrate excluding the indented surface and the edge surface of the resin, the outline surface of the substrate and the edge surface of the resin are level with each other.

35. (New) A semiconductor device, comprising:

a semiconductor chip;

a substrate on which the semiconductor chip is mounted and which is formed by cutting apart a larger substrate, the substrate having an outline surface defining a thickness of the substrate, the substrate having a thinner portion; and

resin for sealing the semiconductor chip, the resin having an edge surface,

wherein the semiconductor device has side surfaces, each of the side surfaces is flat, one of the side surfaces is made of at least the outline surface of the substrate and the edge surface of the resin, the outline surface of the substrate and the edge surface of the resin

are level with each other, a pair of the side surfaces make a corner portion, and the substrate has the thinner portion at the corner portion.

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